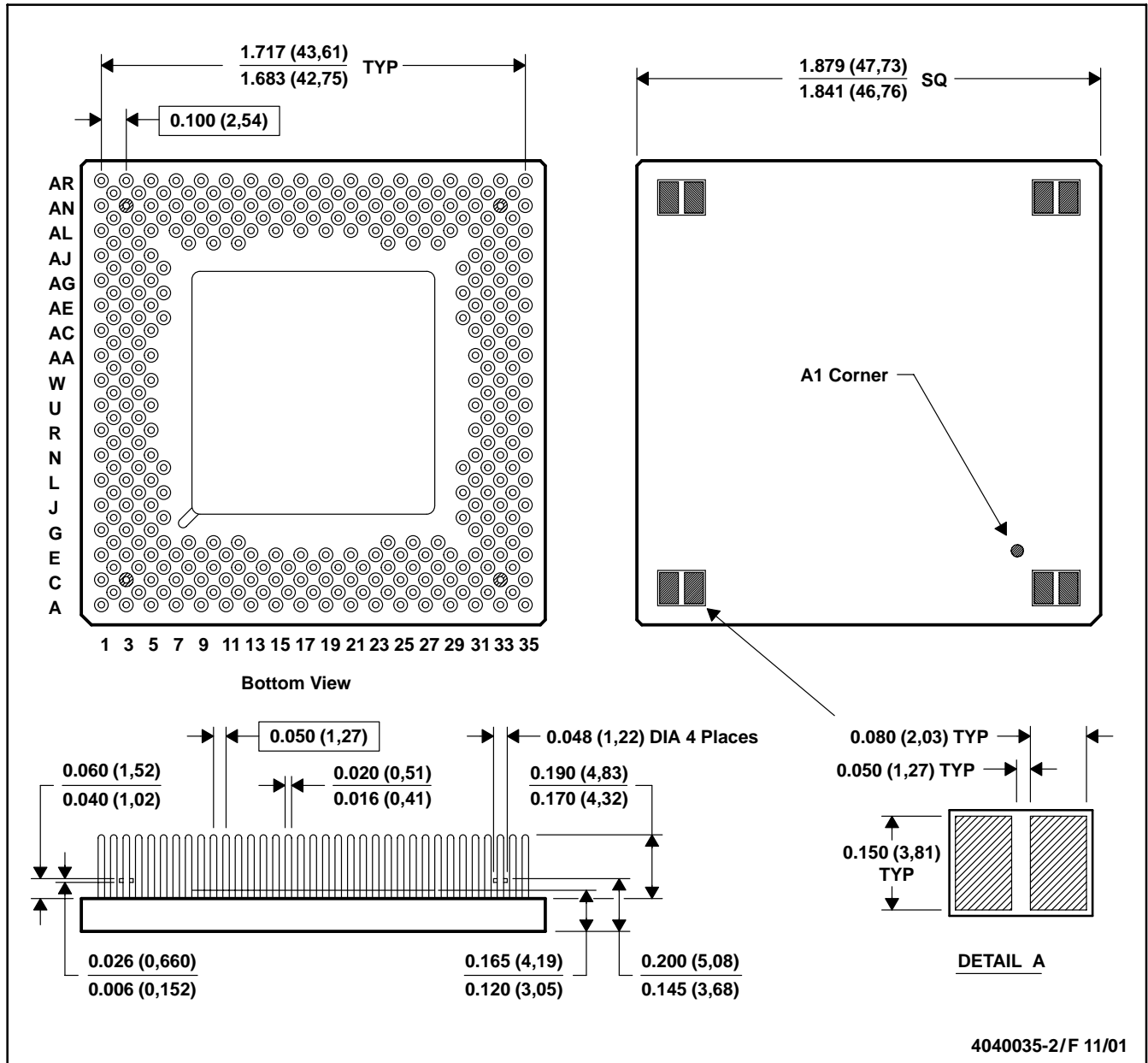


GF (S-CPGA-P325)

CERAMIC PIN GRID ARRAY



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Index mark can appear on top or bottom, depending on package vendor.
 - D. Pins are located within 0.010 (0,25) diameter of true position relative to each other at maximum material condition and within 0.030 (0,76) diameter relative to the edge of the ceramic.
 - E. This package can be hermetically sealed with metal lids or with ceramic lids using glass frit.
 - F. The pins can be gold-plated or solder-dipped.
 - G. Package thickness of 0.165 (4,19) / 0.120 (3,05) includes package body and lid.
 - H. Falls within JEDEC MO-128AK

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